

IN THE CLAIMS:

Claims 9, 10, 12 through 14, 16 through 18, 20, and 21 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

Claims 1-8. (Withdrawn)

205 9. (Presently Amended) A device for establishing electrical contact with a lead element extending from an IC device, comprising:
a ~~substantially planar~~ one-piece substrate bounded by a first substantially planar surface and an opposing, second substantially planar surface and having at least one conductive trace;
a spring contact including a base portion and a contact portion, said contact portion comprising a resiliently compressible coil spring configured to bias against and electrically contact said lead element of said IC device; and
an aperture including a seat portion opening onto said first substantially planar surface of said ~~substantially planar~~ one-piece substrate and a retaining portion having a first end connected to an opposing end of said seat portion and a second end extending a depth at least partially into said ~~substantially planar~~ one-piece substrate, said seat portion of said aperture configured to at least partially contain said contact portion of said spring contact and said retaining portion of said aperture configured to receive and electrically connect said base portion of said spring contact to said at least one conductive trace.

10. (Presently Amended) The device of claim 9, wherein said second end of said retaining portion does not extend entirely through said ~~substantially planar~~ one-piece substrate to said opposing, second substantially planar surface.

11. (Previously Amended) The device of claim 9, further comprising a layer of conductive material disposed on at least a portion of an interior wall of said aperture, said layer of conductive material electrically connecting said base portion of said spring contact to said at least one conductive trace.

12. (Presently Amended) The device of claim 11, wherein said at least one conductive trace is formed on said first substantially planar surface of said ~~substantially planar~~ one-piece substrate.

205 13. (Presently Amended) The device of claim 11, wherein said at least one conductive trace is formed on an intermediate plane within ~~an intermediate conductive plane~~ of said ~~substantially planar~~ one-piece substrate.

14. (Presently Amended) The device of claim 11, wherein said retaining portion of said aperture extends through said ~~substantially planar~~ one-piece substrate and opens onto said opposing, second substantially planar surface of said ~~substantially planar~~ one-piece substrate and said at least one conductive trace is formed on said opposing, second substantially planar surface of said ~~substantially planar~~ one-piece substrate.

15. (Previously Amended) The device of claim 9, further comprising a volume of conductive filler material disposed in and filling at least a partial depth of said aperture and electrically contacting said base portion of said spring contact.

16. (Presently Amended) The device of claim 15, wherein said conductive filler material is electrically connected to said at least one conductive trace of said ~~substantially planar~~ one-piece substrate.

17. (Presently Amended) The device of claim 16, wherein said at least one conductive trace is formed on an intermediate plane within ~~an intermediate conductive plane of said substantially planar~~ said one-piece substrate.

18. (Presently Amended) The device of claim 16, wherein said retaining portion of said aperture extends through said ~~substantially planar~~ one-piece substrate and opens onto said opposing, second substantially planar surface of said ~~substantially planar~~ one-piece substrate and said at least one conductive trace is formed on said opposing, second substantially planar surface of said ~~substantially planar~~ one-piece substrate.

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19. (Canceled)

20. (Presently Amended) The device of claim 9, wherein said second end of said retaining portion opens onto said opposing, second substantially planar surface of said ~~substantially planar~~ one-piece substrate.

21. (Presently Amended) The device of claim 9, wherein said seat portion comprises a generally hemispherical recess formed in said first substantially planar surface of said ~~substantially planar~~ one-piece substrate, a generally conical recess formed in said first substantially planar surface of said ~~substantially planar~~ one-piece substrate, or a generally cylindrical recess formed in said first substantially planar surface of said ~~substantially planar~~ one-piece substrate.

22. (Previously Amended) The device of claim 9, wherein said seat portion is further configured to at least partially align said lead element of said IC device relative to said spring contact.

23. (Previously Amended) The device of claim 9, wherein said contact portion of said spring contact comprises a resiliently compressible coil spring having at least two spring coils for contacting portions thereof and configured to bias against and electrically contact said lead element of said IC device.

Claims 24-45. (Withdrawn)
